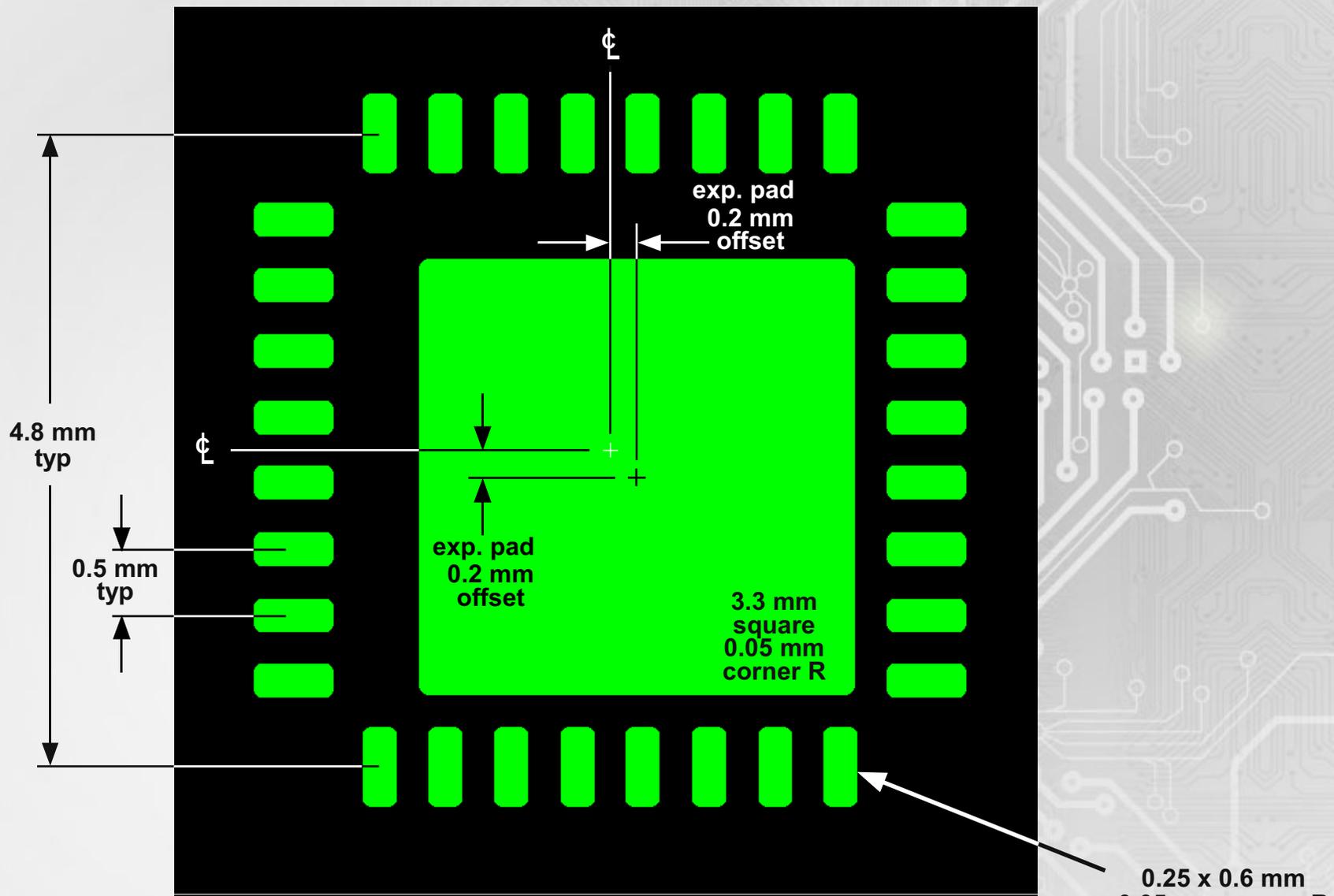


# RHB0032H Land Pattern Example

Analog Packaging

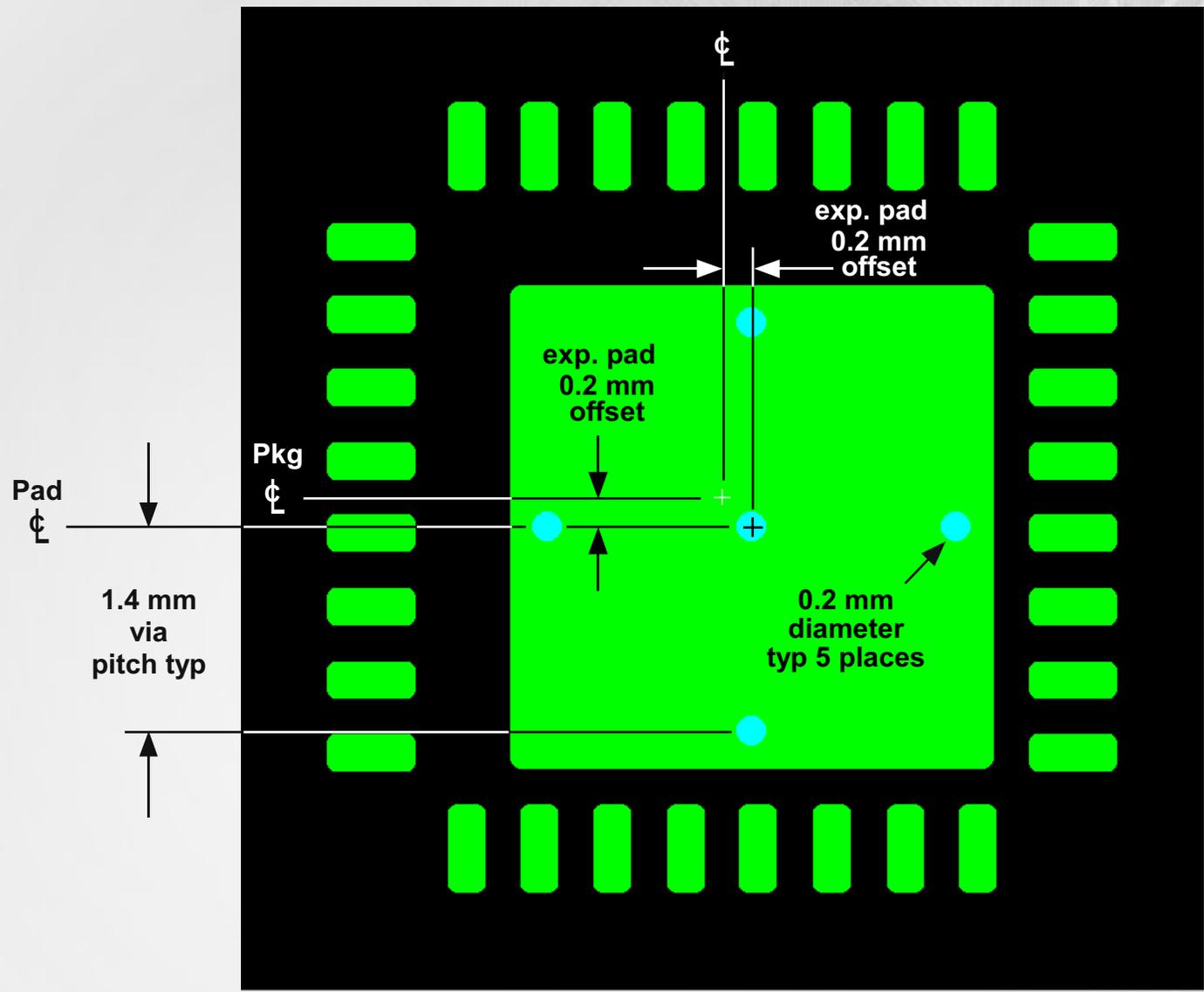
26-Nov-2014



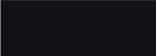
# TOP ETCH

= Exposed FR4
  = Exposed metal

**NOTE:**  
Refer to package mechanical drawing at the website for complete mechanical dimensions.

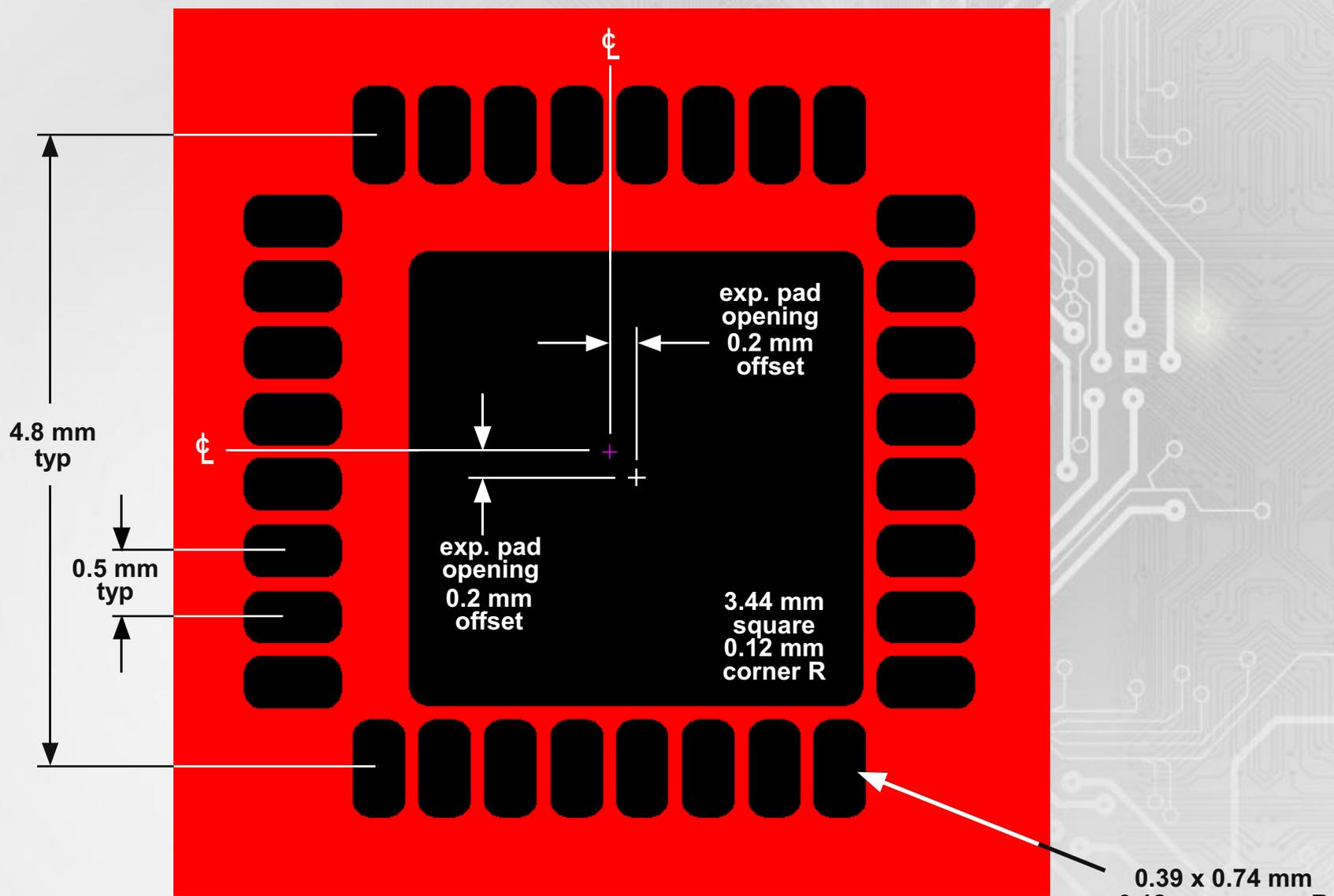


## TOP ETCH with THERMAL VIAS

 = Exposed FR4

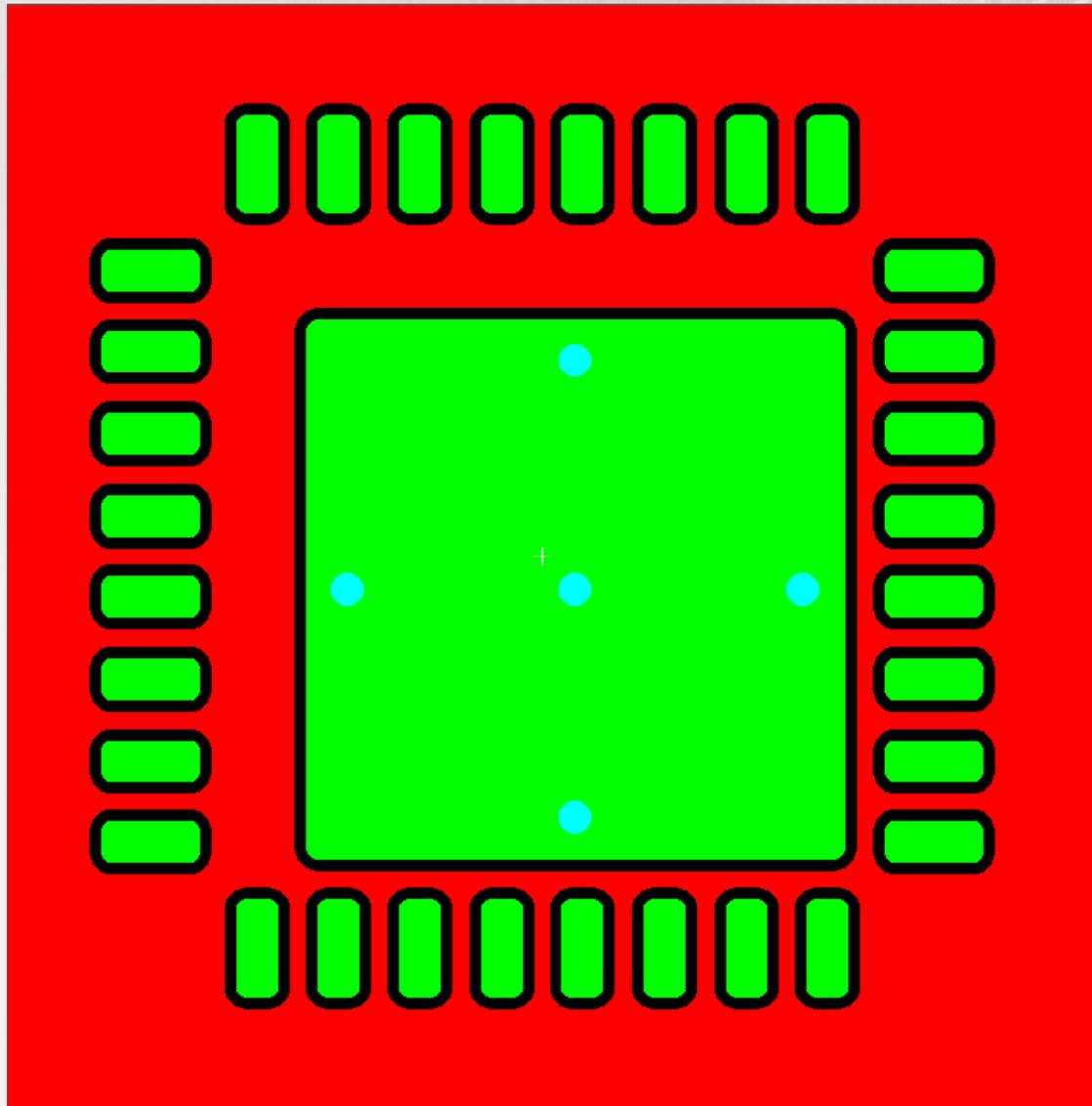
 = Exposed metal

 = Thermal Vias

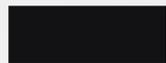


# TOP SOLDERMASK

- = Exposed FR4
- = Mask over FR4



## TOP ETCH + SOLDERMASK + VIAS



= Exposed FR4



= Exposed metal

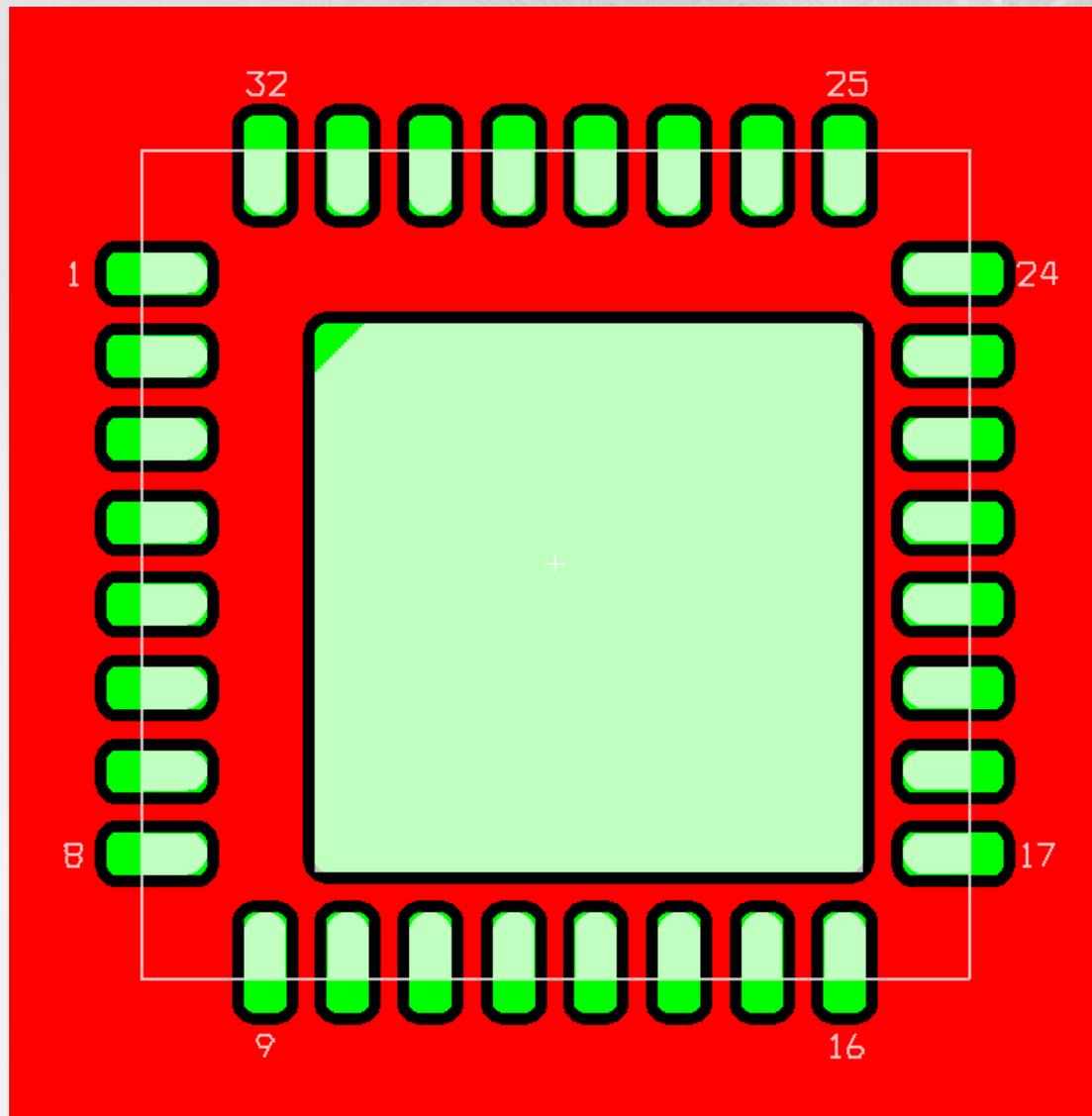


= Thermal Vias



= Mask over FR4



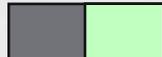


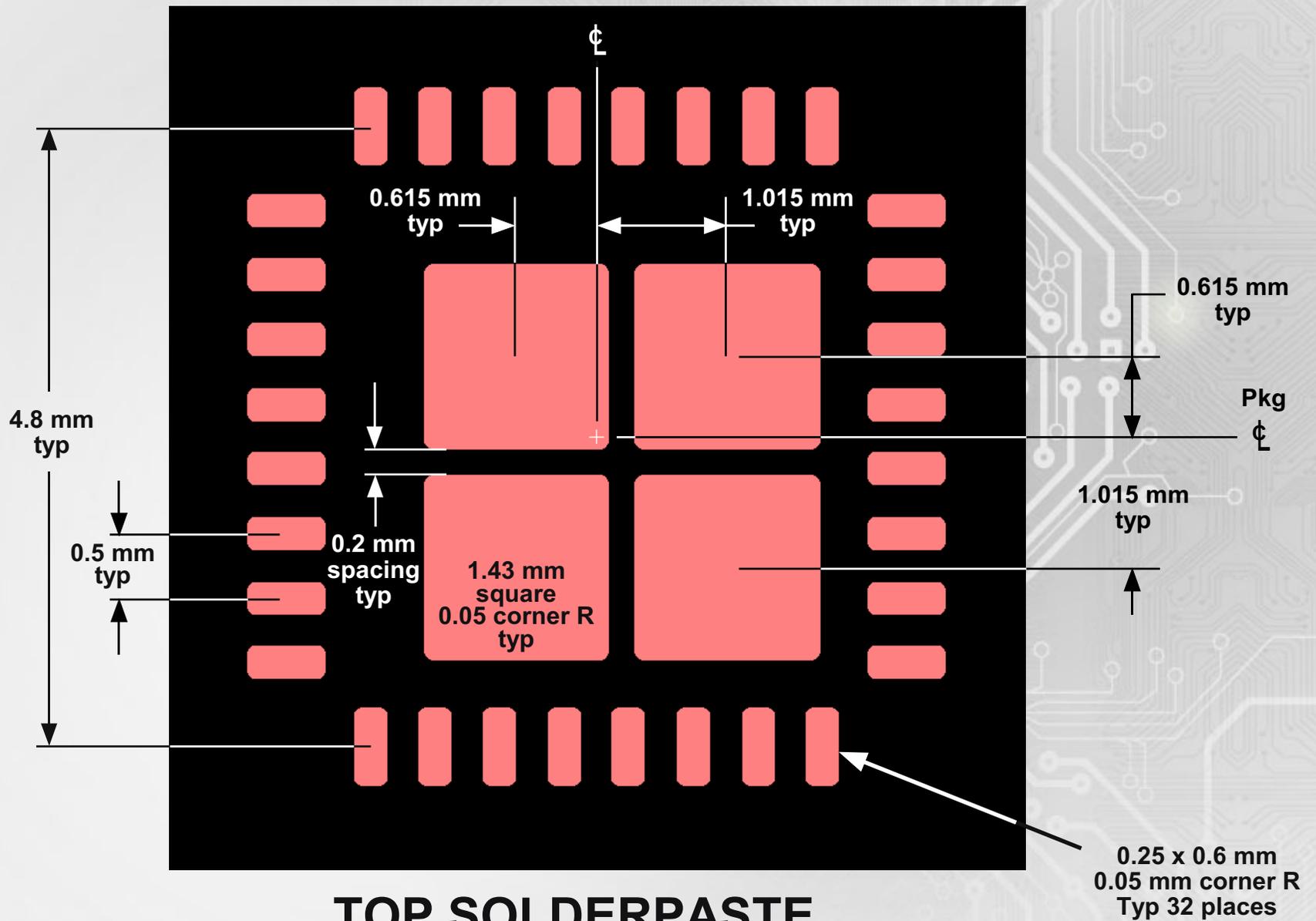
## PACKAGE ON FOOTPRINT

 = Exposed FR4

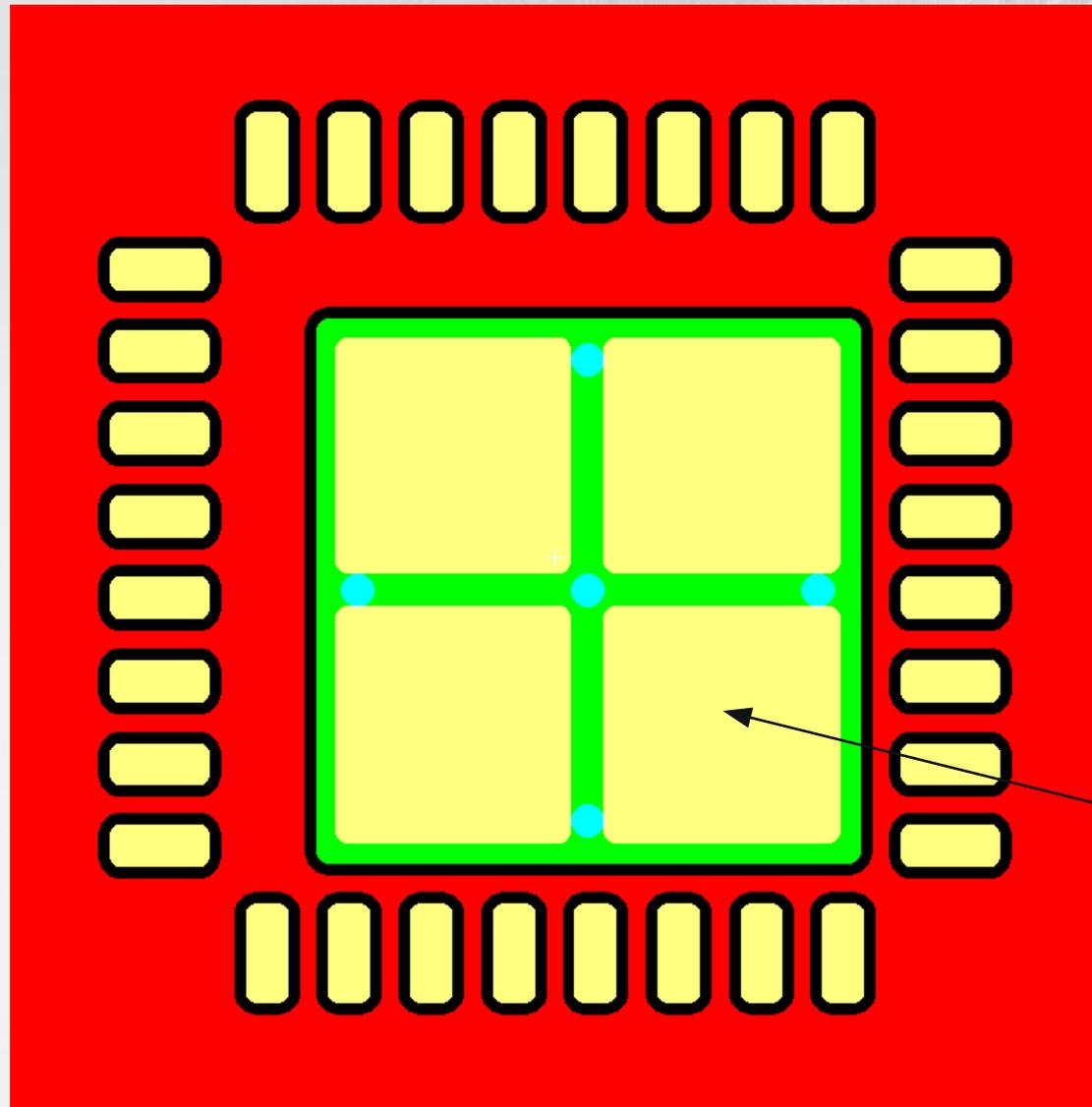
 = Exposed metal

 = Mask over FR4

 = Package pads



**Note:**  
 Recommended stencil thickness is 0.127 mm (0.005") to allow proper deposition of the solderpaste.



75% exposed pad paste coverage

## TOP ETCH + SOLDERMASK + SOLDERPASTE + VIAS

 = Exposed FR4

 = Exposed metal

 = Thermal Vias

 = Mask over FR4

 = Paste over Metal